

Product Parameter	
Item	Capability
Layers	1-40
Thicker Copper	1-6OZ
Products Type	HF(High-Frequency)&(Radio Frequency) board, Impedance controlled board , HDI board ,BGA& Fine Pitch board
Solder Mask	Nanya&Taiyo ;LPI & Matt Red, green, yellow,white, blue,black.
Base material	FR4(Shengyi China,ITEQ, KB A+,HZ), HI-TG, FR06, Rogers,Taconic,Argon,Nalco,Isola and so on
Finished Surface	Conventional HASL,Lead-free HASL,Falsh Gold, ENIG (Immersion Gold)OSP(Entek), Immersion Tin,ImmersionSilver,Hard Gold
Selective Surface	ENIG(immersion Gold)+OSP, ENIG(immersion Gold)+Gold Finger,Flash Gold +Gold Finger, immersion Silver+ Gold Finger, Immersion
Treatment	Tin+Gold Finger
Technical Specification	Minimum line width/gap:3.5/4mil(laser drill)
	Minimum hole size:0.15mm(mechanical drill)/4mil(laser drill)
	Minimum Annular Ring: 4mil
	Max Copper thickness: 6OZ
	Max Production size:900×1200mm
	Board Thickness:D/S: 0.2-7.0mm, Multilayers:0.40-7.0mm,
	Min Solder Mask Bridge:0.08mm
	Aspect ratio: 15:1
	Plugging Visa capability: 0.2-0.8mm
Tolerance	Plated holes Tolerance:0.08mm(min±0.05)
	Non-plated hole tolerance:0.05min(min+0/-0.05mm or +0.05/-0mm)
	Outline Tolerance:0.15min(min±0.10mm)
	Functional test :
	Insulating resistance : 50 ohms (mormality)
	Peel off strength: 1.4N/mm
	Thermal Stress test :2650c,20 seconds
	Solder mask hardness:6H
	E-Test voltage :500V+15/-0V 30S
	Warp and Twist: 0.7% (semiconductor test board≤0.3%)